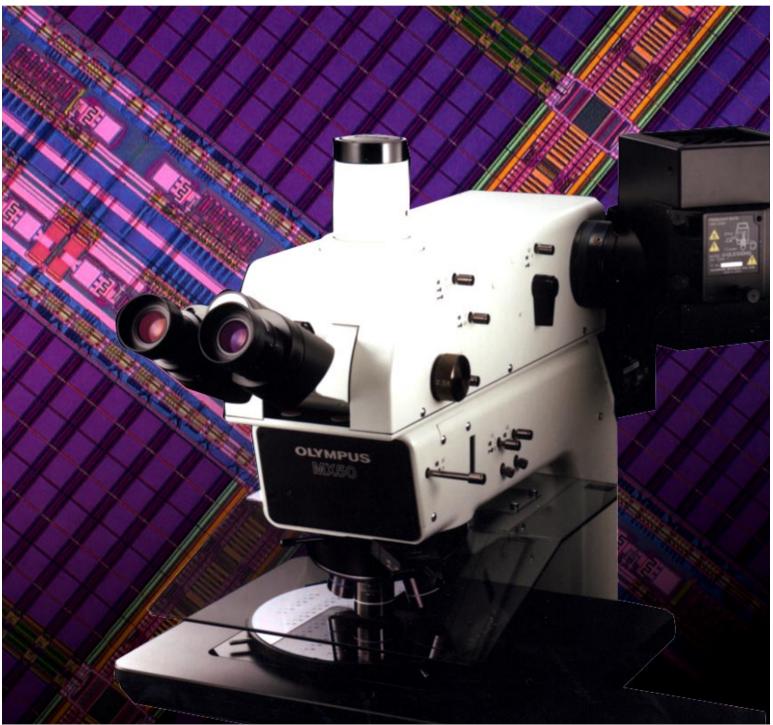
OLYMPUS®

Olympus is about life. About photographic innovations that capture precious moments of life. About advanced medical technology that saves lives. About information- and industry-related products that make possible a better living. About adding to the richness and quality of life for everyone. Olympus. Quality products with a **FOCUSON LIFE**

REAL-TIME CONFOCAL MICROSCOPE



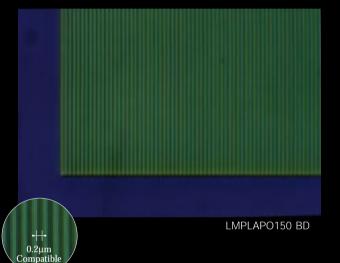




Clear Observation of Intricate Patterns

Confocal Mode (CF1)

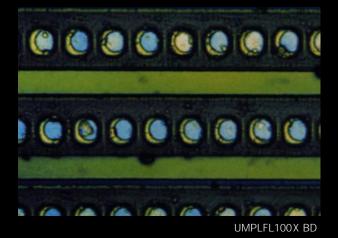
Non-confocal Observation, Brightfield Mode





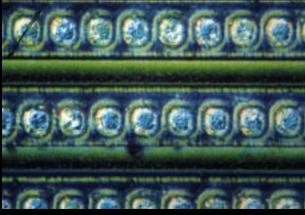
Sharp Profile Images Right to the Edge

Confocal Mode / Contact Hole



Ideal for Inspecting Delicate Gaps and Warps

Confocal DIC Mode / Contact Hole

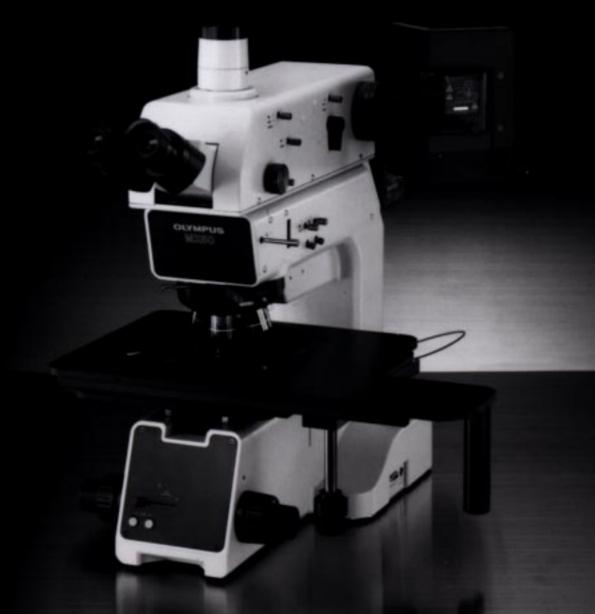


UMPLFL100X BDP



Innovations in Optics Set New Standards in Brightness and Confocal Performance

Developed through an advanced and comprehensive R & D program, the MX50-CF real-time confocal microscope sets new standards for both lateral/axial resolution and brightness in real-time confocal inspections. The system combines sophisticated Olympus UIS optics, already highly rated within the semiconductor industry, with the Nipkow Disk to further extend the instrument's confocal performance potential. With its high-intensity white light source and advanced light loss control capability, the MX50-CF leads its class in the critical areas of brightness and resolution, providing color information which conventional laser confocal microscopes cannot convey. This superior performance is of unrivaled value in the 0.18µm rule inspection of today's increasingly minimized and multi-layered LSI patterns.



The Real-time Confocal Microscope that Leads the Way in Image Clarity and Operability

The Ideal Combination for Confocal Microscopy: Nipkow Disk and UIS Optics

With images scanned by the Nipkow Disk and enhanced by the superior technological performance of Olympus UIS optics, the MX50-CF provides outstanding real-time confocal observation – accurately resolving original images of less than 0.25μ m. Images are further clarified by sectioning effects which allow easy inspection of bottom layers in multi-layer specimens and pinhole bottoms – all with unparalleled higher resolution and higher contrast than any other microscope in this class.

Maximized Brightness Ensures Excellent Image Clarity Even at the Highest Magnifications

The incorporation of superior optical components and a higher mirror reflection factor enables the MX50-CF to minimize light loss and give significantly improved brightness during confocal observation. Bright images are achieved even under high magnification (e.g. via a 150x objective lens), making observation on monitor easier than ever.

A Range of Observation Modes Including Original Confocal DIC Microscopy

Four observation modes are available. Selection is at the touch of a lever for CF1 mode (priority on brightness for good color reproduction of the specimen), CF2 mode (priority on axial resolution power for sectioning effects), or BF mode (brightfield observation). Nomarski DIC microscopy can also be selected for confocal effects: with the DIC prism slider IN and the /4 tint plate knob at OUT, the user can clearly observe and distinguish delicate textures that could not be recognized in general confocal modes.

Direct Path Ensures Clear Images in Conventional Microscopy

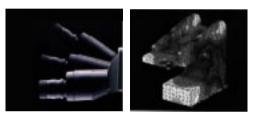
The MX50-CF allows easy switching between confocal image/non confocal observation. The direct observation path used during conventional microscopy procedures prevents image deterioration because the image does not have to go through the confocal contour relay path. The result is clear images – every time. Intermediate magnification factors contained for high magnification observation

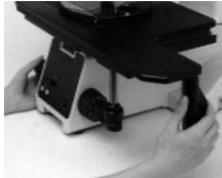
Tilting observation tube for comfortable operation Frontal layout for ease of use

High-rigidity, anti-shock design for high magnification observation without disturbance

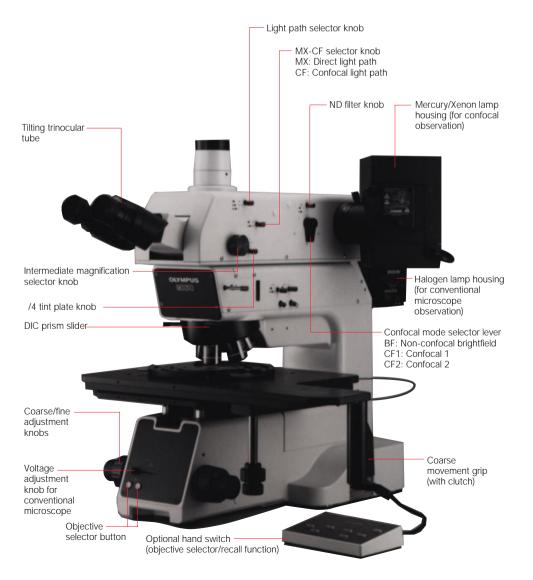
Greater color accuracy than conventional confocal microscopes: The MPLAPO objectives present images in colors closer to those of the actual specimen Add-on to the MX50 for excellent operability CE accredited

Major applications: bottom layer in multi-layer structures and metal layer on patterned wafer, magnetic head and new/metallic materials







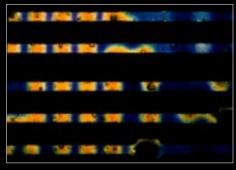


Unrivaled Levels of Resolution and Contrast Achieved by Confocal Image and Microscope Image

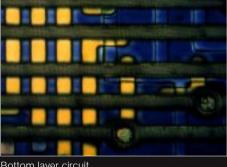
Top layer circuit

MPLAPO100X BD

Non-confocal observation, brightfield mode

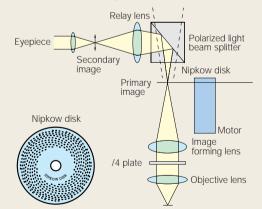


Top layer circuit Confocal mode (CF2) UMPLFL100X BD



Bottom layer circuit Confocal mode (CF1) UMPLFL100X BD

Real-time Confocal Optics

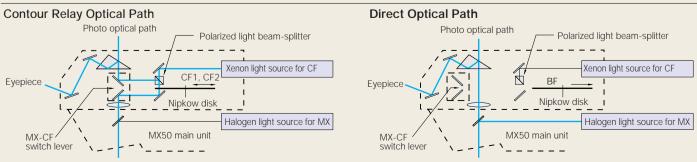


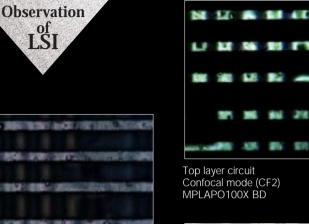
Fundamentals Of Real-time Confocal Optics

The MX50-CF's confocal scanning method is based on use of the Nipkow Disk. The Nipkow Disk has numerous pinholes on its primary image-forming disk: light passing through the pinholes is reflected off the specimen and back to the pinholes. However, since the pinholes are located on the primary image-forming disk, only light reflected onto the focused disk is transmitted through the pinholes: this is the confocal effect.

When the disk is rotated at high speed, the light beams passing through the pinholes will scan the specimen simultaneously; this allows a real-time image to be observed, as with an ordinary optical microscope. There are also two pinhole diameters on the disk; switching between them adjusts the confocal effects.

In conventional microscopy, illumination optics have not always been adequate for the high magnifications required for confocal observations; in particular, there tended to be insufficient brightness for accurate, detailed observation. To overcome this problem, Olympus has developed significant refinements to the illumination optics combined them with UIS optics to achieve today's highest standards of brightness and confocal effects.







1.1

Bottom layer circuit Confocal mode (CF1) MPLAPO100X BD

Meeting Diverse Needs in Semiconductor Inspection: A Line-up that Only OLYMPUS Can Offer

As well as offering excellent performance as a stand-alone unit, the Olympus real-time confocal semiconductor inspection microscope can be combined with a wafer loader, making it a mini workstation, or upgraded to the AL1000 flexible wafer inspection system by the addition of an automatic stage.

Olympus will continue to maintain its commitment to developing innovative systems based on real-time confocal semiconductor inspection microscopes — systems that meet our customers' diverse needs for clear, accurate, high-resolution inspection.



MX50-CF

Wafer loader+Manual wafer inspection

Integrated wafer inspection under recipe control

MX50-CF + AL100

Real-time Confocal Microscope + Wafer Loader

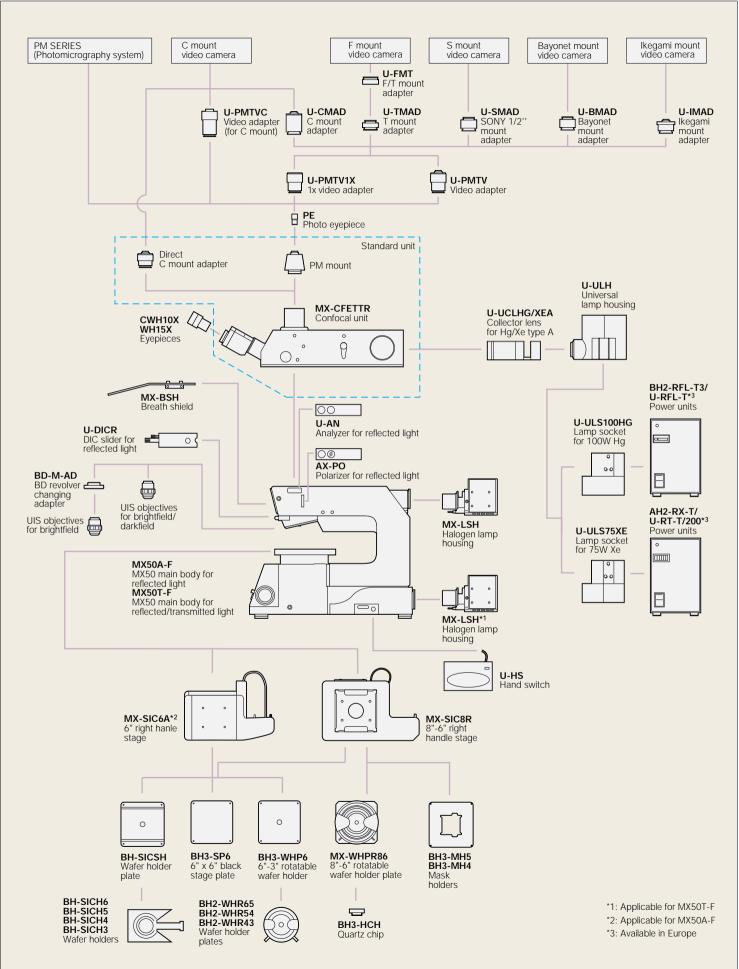
Combining the MX50-CF with the AL100 wafer loader series (which offers the world's first micro/macro/back side 3inspection feature) creates a mini workstation that 0.18µm compatible. Additional advantages include cost-effective performance and excellent space efficiency in clean room working environments.

AL1000

Flexible Wafer Inspection System

This powerful system is for inspecting super micro structures like the 64M DRAM. Wafer observation software is offered in menu form for stage-by-stage operation, and settings for sampling, die map, inspection time, microscopy method and objective magnification factor can all be made at the touch of a button.

SYSTEM DIAGRAM



MX50-CE specifications

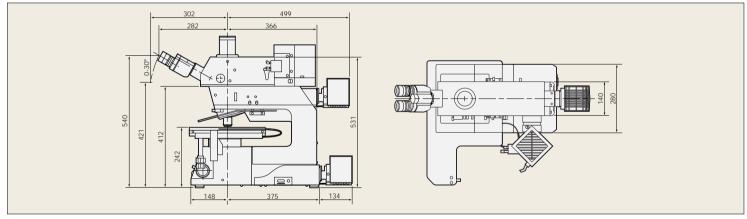
Item		specifications						
Microscope stand	Frame	8" arm-integrated frame with built-in transformer for reflected or reflected/transmitted light (switchable), and power supply for driving motorized revolving nosepiece						
	Focus	Coaxial coarse and fine focus controls, vertical stage travel range: 32mm (2mm up and 30mm down from focus position) Fine focus stroke per rotation: 0.1mm, minimum fine focus adjustment graduation: 1μm, sensitivity: 1μm or less						
	Revolving nosepiece	Hi-speed motorized quintuple nosepiece for brightfield/darkfield observations (adapter required for brightfield objectives)						
	Incident illumination	100W Hg or 75W Xe light source (for confocal observation) 12V, 100W halogen bulb light source (for non-confocal observation)						
	Stage	Stroke: 210 x 210mm roller guide slide mechanism (with use of MX-SIC8R) Belt drive system (no rack) Grip clutch function (vacuum stages mountable when combined with a wafer loader)						
	Objectives	UIS objectives						
	Eyepieces	CWH10X or WH15X						
CF unit	Observation tube	Erect widefield tilting trinocular observation tube (0-30 degrees), F.N. 20						
	Observation method	 (1)Confocal observation CF1 (pinhole diameter: φ45μm) (2)Confocal observation CF2 (pinhole diameter: φ25μm) (3)Confocal DIC observation (for CF1 and CF2) (4)Non-confocal observation (brightfield/darkfield, Nomarski DIC) 						
	Intermediate magnification	Three steps selectable: 1.67x, 2x, 2.5x (BI) 1x, 1.2x, 1.5x (Photo tube)						
Dimensions and weight		See diagram, approx. 55kg						

Objectives specifications

		N.A.	W.D.(mm)			N.A.	W.D.(mm)			N.A.	W.D.(mm)			N.A.	W.D.(mm)
UMPLFL	5x	0.15	20.0	UMPLFL	5xBDP	0.15	12.0	LMPLFL	5x	0.13	22.5	MPLAPO	2.5x	0.08	10.7
	10x	0.30	10.1		10xBDP	0.25	6.5		10x	0.25	21.0		20x	0.60	0.9
	20x	0.46	3.1		20xBDP	0.40	3.0		20x	0.40	12.0		50x	0.95	0.3
	50x	0.80	0.66		50xBDP	0.75	0.66		50x	0.50	10.6		100x*	0.95	0.35
	100x	0.95	0.31		100xBDP	0.90	0.31		100x	0.80	3.4		100xBD*	0.9	0.31
	5xBD	0.15	12.0	SLMPL	20x	0.35	21.0		5xBD	0.13	15.0	LMPLAPO	150x*	0.9	1.0
	10xBD	0.30	6.5		50x	0.45	15.0		10xBD	0.25	10.0		150xBD*	0.9	1.0
	20xBD	0.46	3.0					:	20xBD	φ.40	12.0		250x	0.9	0.8
	50xBD	0.80	0.66						\$0xBD	φ.50	10.6		250xBD	0.9	0.8
	100xBD	0.90	0.31						100xBD	ф.80	3.3				

* Recommended for high resolution confocal microscopy.

Dimensions (unit: mm)



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Specifications are subject to change without any obligation on the part of the manufacturer.

Olympus business areas Medical and health-care area Imaging and information area Industrial OLYMPUS AUSTRALIA PTY LTD. 31 Gilby Road, Mount Waverley, Victoria, 3149, Australia applications area

